

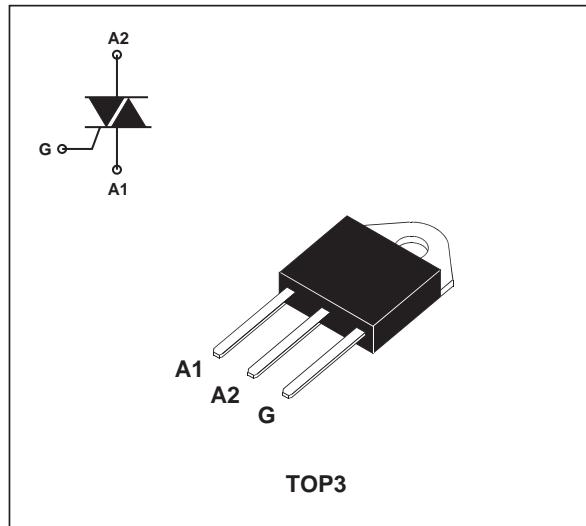
ALTERNISTORS

FEATURES

- High commutation: > 88A/ms (400Hz)
- Insulating voltage = 2500V_(RMS) (UL Recognized: EB81734)
- High voltage capability: V_{DRM} = 1200V

DESCRIPTION

The TPDV625 ---> TPDV1225 use a high performance passivated glass alternistor technology. Featuring very high commutation levels and high surge current capability, this family is well adapted to power control on inductive load (motor, transformer...)


ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I _{T(RMS)}	RMS on-state current (360° conduction angle)	25	A
I _{TSM}	Non repetitive surge peak on-state current (T _j initial = 25°C)	tp = 2.5ms	A
		tp = 8.3ms	
		tp = 10ms	
I ² t	I ² t value	265	A ² s
dI/dt	Critical rate of rise of on-state current Gate supply: I _G = 500mA dI _G /dt = 1A/μs	Repetitive F = 50Hz	A/μs
		Non repetitive	
T _{stg} T _j	Storage and operating junction temperature range	-40 to +150 -40 to +125	°C
T _l	Maximum lead soldering temperature during 10s at 4.5mm from case	260	°C

Symbol	Parameter	TPDV				Unit
		625	825	1025	1225	
V _{DRM} V _{RRM}	Repetitive peak off-state voltage T _j = 125°C	600	800	1000	1200	V

TPDV625 ---> TPDV1225

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-a)	Contact to ambient	50	°C/W
R _{th} (j-c) DC	Junction to case for DC	1.5	°C/W
R _{th} (j-c) AC	Junction to case for 360° conduction angle (F = 50Hz)	1.1	°C/W

GATE CHARACTERISTICS (maximum values)

P_{G(AV)} = 1W P_{GM} = 40W (tp = 20μs) I_{GM} = 8A (tp = 20μs) V_{GM} = 16V (tp = 20μs)

ELECTRICAL CHARACTERISTICS

Symbol	Test conditions	Quadrant		Value	Unit	
I _{GT}	V _D = 12V (DC) R _L = 33Ω	T _j = 25°C	I - II - III	MAX.	150	mA
V _{GT}	V _D = 12V (DC) R _L = 33Ω	T _j = 25°C	I - II - III	MAX.	1.5	V
V _{GD}	V _D = V _{DRM} R _L = 3.3kΩ	T _j = 125°C	I - II - III	MIN.	0.2	V
tgt	V _D = V _{DRM} I _G = 500mA dI _G /dt = 3A/μs	T _j = 25°C	I - II - III	TYP.	2.5	μs
I _L	I _G = 1.2I _{GT}	T _j = 25°C	I - III	TYP.	100	mA
			II		200	
I _H *	I _T = 500mA Gate open	T _j = 25°C		TYP.	50	mA
V _{TM} *	I _{TM} = 35A tp = 380μs	T _j = 25°C		MAX.	1.8	V
I _{DRM} I _{RRM}	V _{DRM} rated V _{RRM} rated	T _j = 25°C		MAX.	0.02	mA
		T _j = 125°C		MAX.	8	
dV/dt *	Linear slope up to V _D = 67% V _{DRM} gate open	T _j = 125°C		MIN.	500	V/μs
(dI/dt)c*	(dV/dt)c = 200V/μs	T _j = 125°C		MIN.	20	A/ms
	(dV/dt)c = 10V/μs				88	

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

Fig. 1: Maximum RMS power dissipation versus RMS on-state current ($F = 50\text{Hz}$). (Curves are cut off by $(dI/dt)c$ limitation)

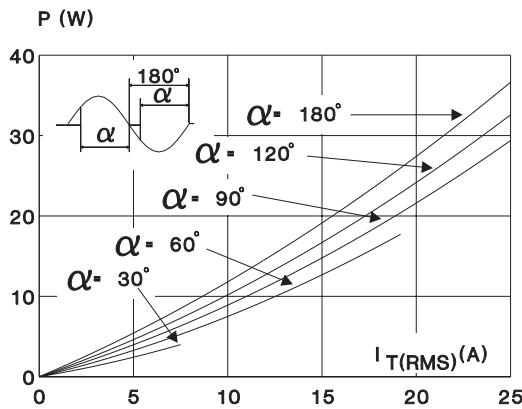


Fig. 3: RMS on-state current versus case temperature.

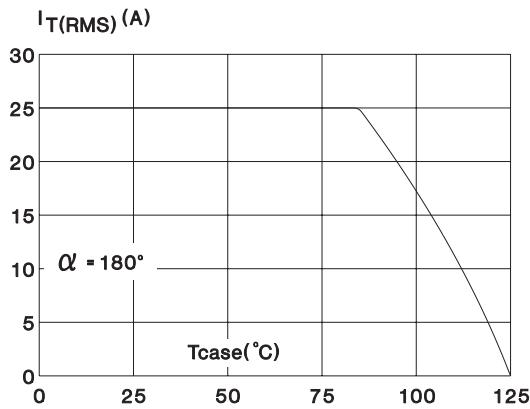


Fig. 5: Relative variation of gate trigger current and holding current versus junction temperature.

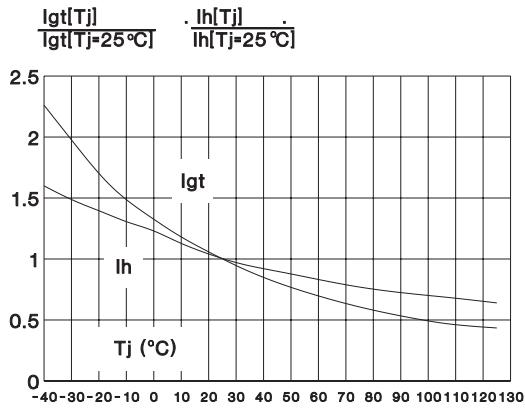


Fig. 2: Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

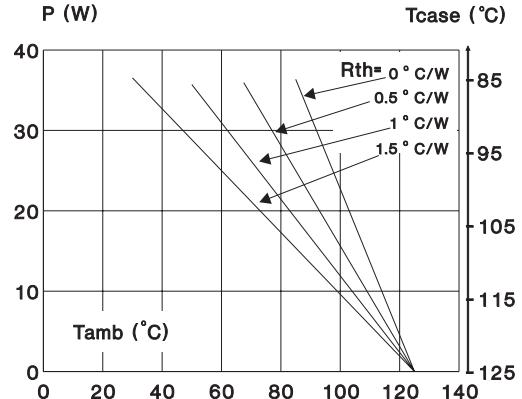


Fig. 4: Relative variation of thermal impedance versus pulse duration.

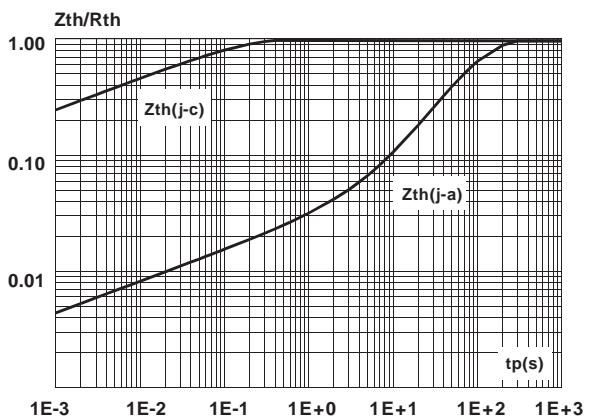
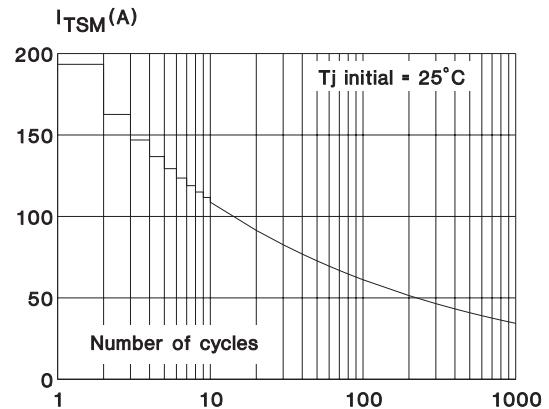


Fig. 6: Non repetitive surge peak on-state current versus number of cycles.



TPDV625 ---> TPDV1225

Fig. 7: Non repetitive surge peak on-state current for a sinusoidal pulse with width: $t \leq 10\text{ms}$, and corresponding value of I^2t .

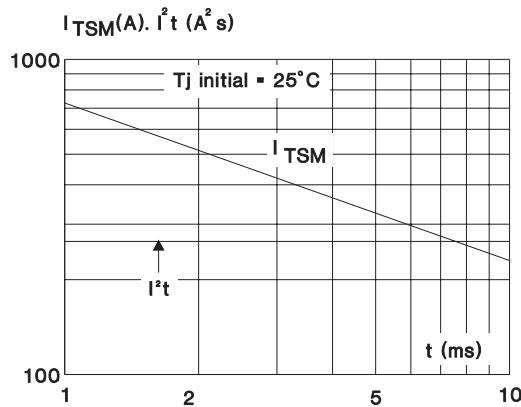


Fig. 8: On-state characteristics (maximum values).

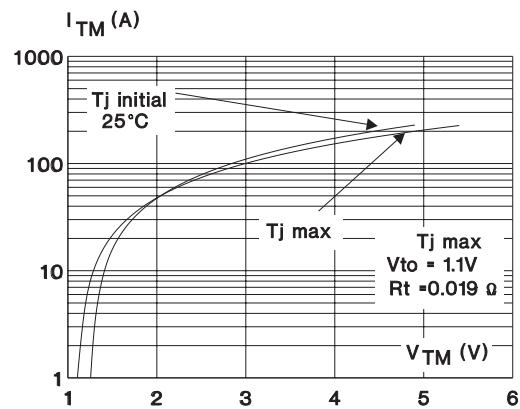
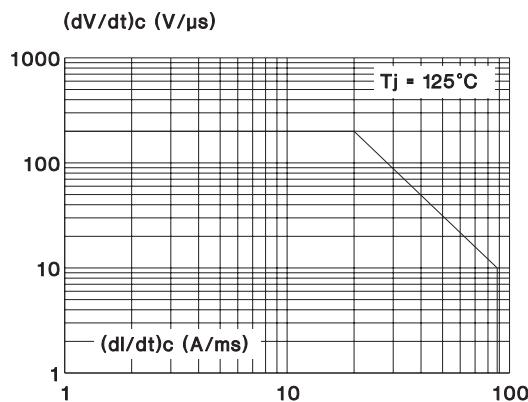


Fig. 9: Safe operating area.



PACKAGE MECHANICAL DATA
TOP3 (Plastic)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	1.45	1.55	0.057	0.061
C	14.35	15.60	0.565	0.614
D	0.5	0.7	0.020	0.028
E	2.7	2.9	0.106	0.114
F	15.8	16.5	0.622	0.650
G	20.4	21.1	0.815	0.831
H	15.1	15.5	0.594	0.610
J	5.4	5.65	0.213	0.222
K	3.4	3.65	0.134	0.144
L	4.08	4.17	0.161	0.164
P	1.20	1.40	0.047	0.055
R	4.60 Typ.		0.181 Typ.	

OTHER INFORMATION

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
TPDVx25	TPDVx25	TOP3	4.5 g	120	Bulk

- Epoxy meets UL94,V0
- Cooling method: C
- Recommended torque value: 0.8 m.N.
- Maximum torque value: 1 m.N.

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